



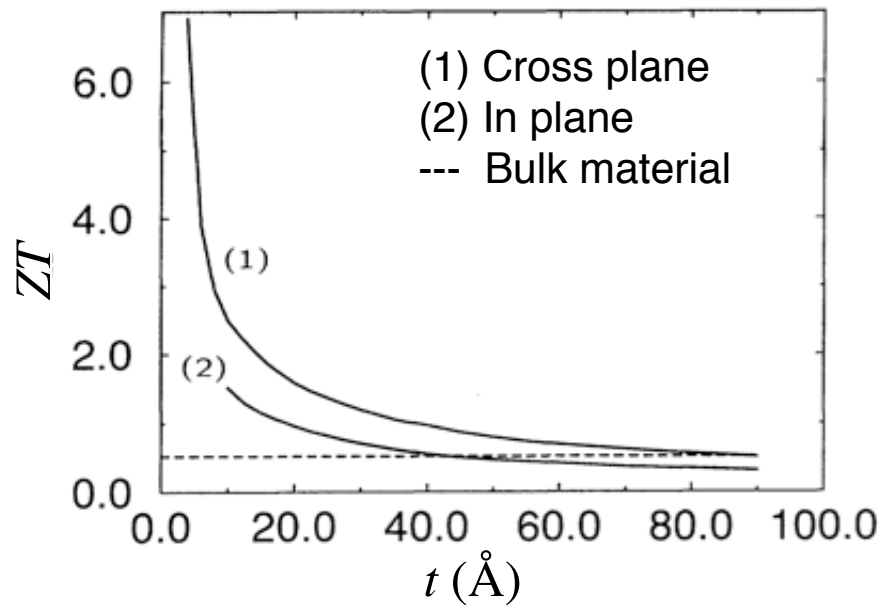
MRS Spring meeting San Francisco April 2014  
Symposium A. Film-silicon science and technology

## **Silicon-based thin films and 0–3 composites with very low thermal conductivity**

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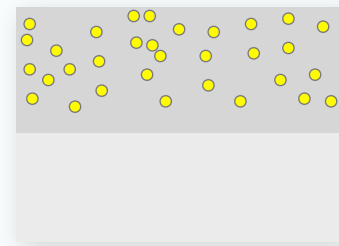
# Control of thermoelectric properties



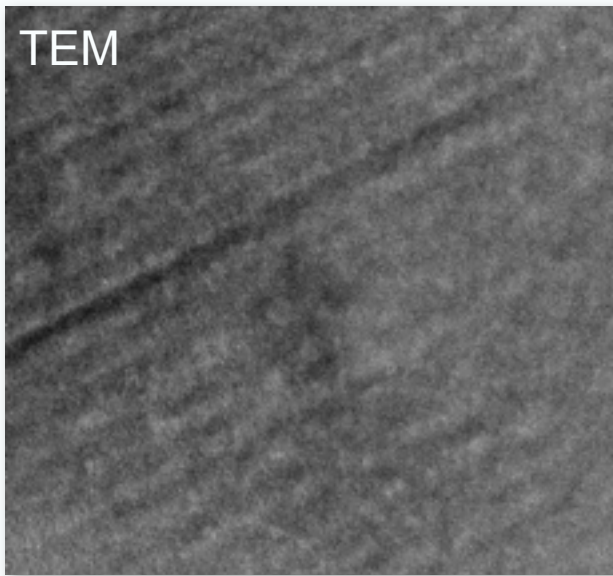
$$ZT = \frac{S^2 \sigma}{\kappa} T$$

Thermoelectric figure of merit  $ZT$  for anisotropic  $\text{Bi}_2\text{Te}_3$  layers of the thickness  $t$  [Hicks, Dresselhaus 1993]

**Superlattices, random multilayers, composites, quantum dot SLs**

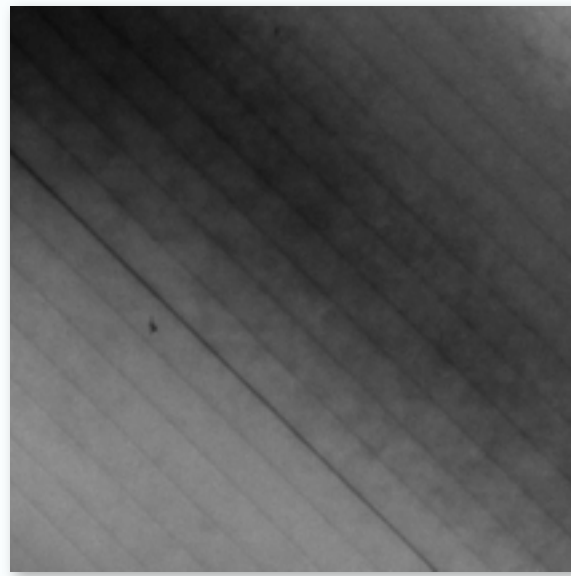


# Si-Si<sub>1-x</sub>Ge<sub>x</sub> superlattices



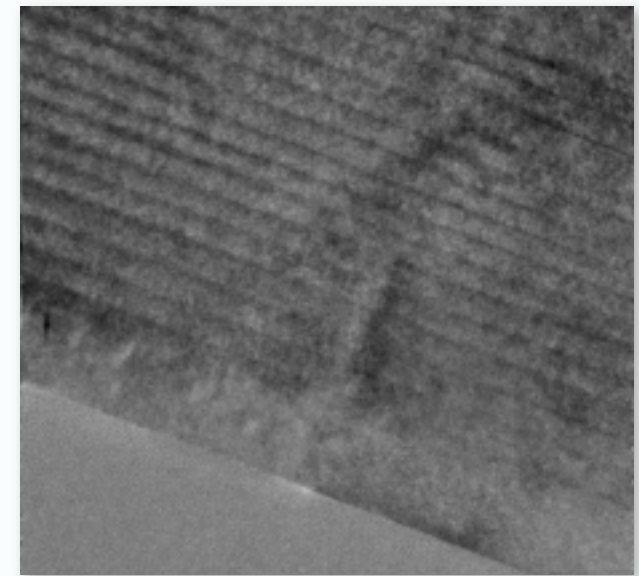
10 nm

0.2 nm Ge + 3.3 nm Si  
171×, ≈ 600 nm



50 nm

1.6 nm Ge + 12 nm Si  
39×, ≈ 600 nm



10 nm

2 nm Ge + 1.5 nm Si  
171×, ≈ 600 nm

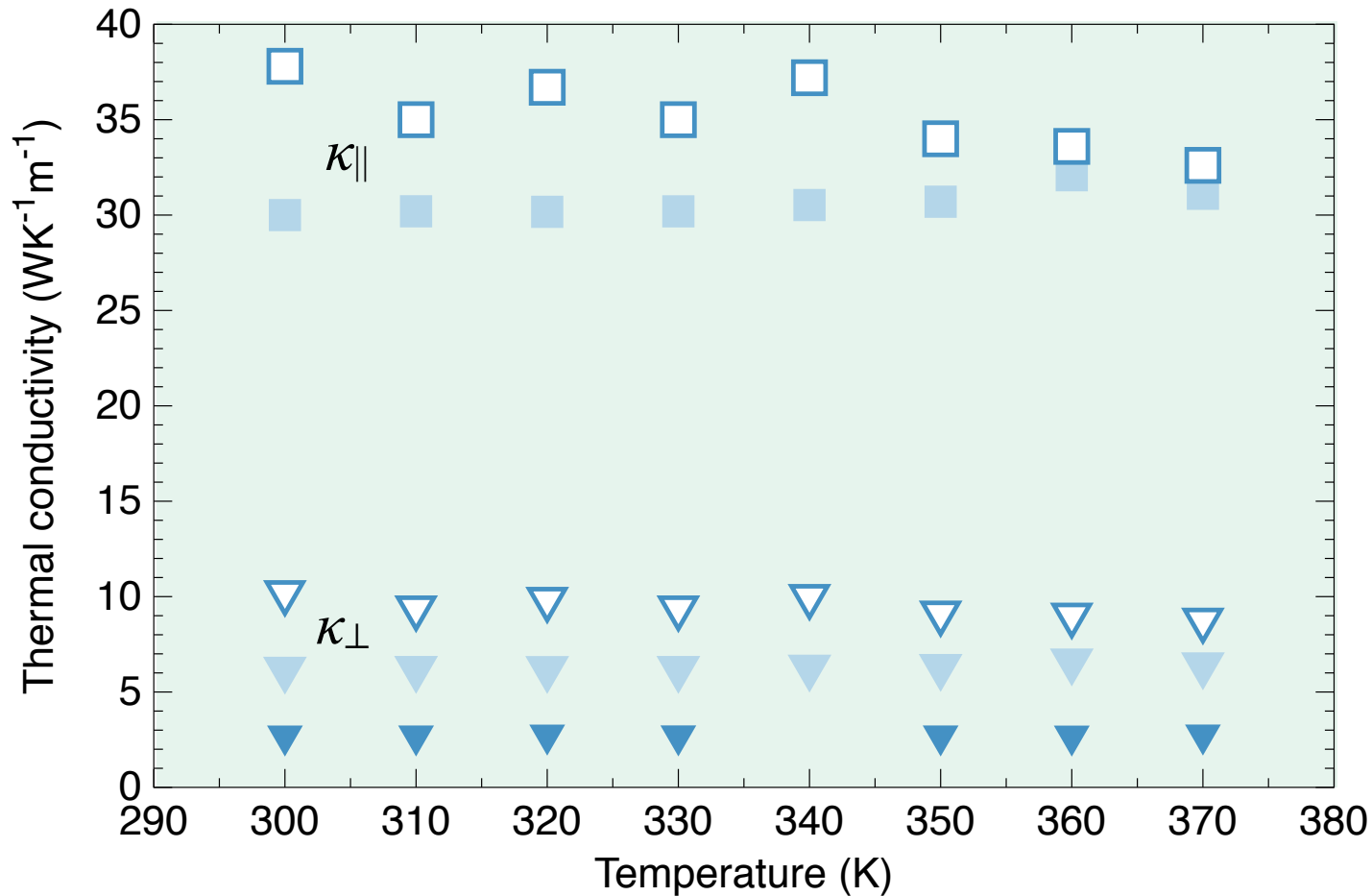
Average Ge content

1.7 %

3.5 %

17 %

# Thermal conductivity of superlattices



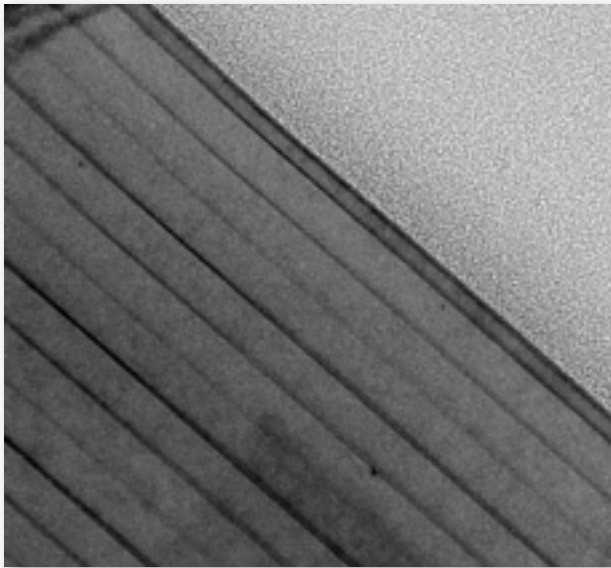
3.5 % Ge, period 13.6 nm  
1.7 % Ge, period 4.5 nm

3.5 % Ge, period 13.6 nm  
1.7 % Ge, period 4.5 nm  
17 % Ge, period 4.5 nm

In-plane ( $\kappa_{\parallel}$ ) and cross-plane ( $\kappa_{\perp}$ ) thermal conductivities for superlattices with different Ge contents and periods

# Random multilayers

20 nm  
        



1.2 nm Ge + 12 nm Si

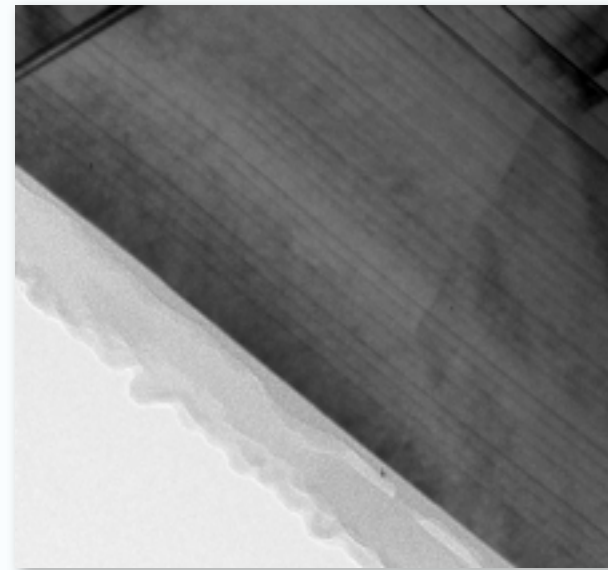
1.2 nm Ge + 12 nm Si

1.8 nm Ge + 12 nm Si

0.9 nm Ge + 12 nm Si

1.6 nm Ge + 12 nm Si

6x,  $\approx$  600 nm



0.6 nm Ge + 4.1 nm Si

0.3 nm Ge + 5.1 nm Si

0.8 nm Ge + 4.8 nm Si

0.6 nm Ge + 5.7 nm Si

0.6 nm Ge + 3.8 nm Si

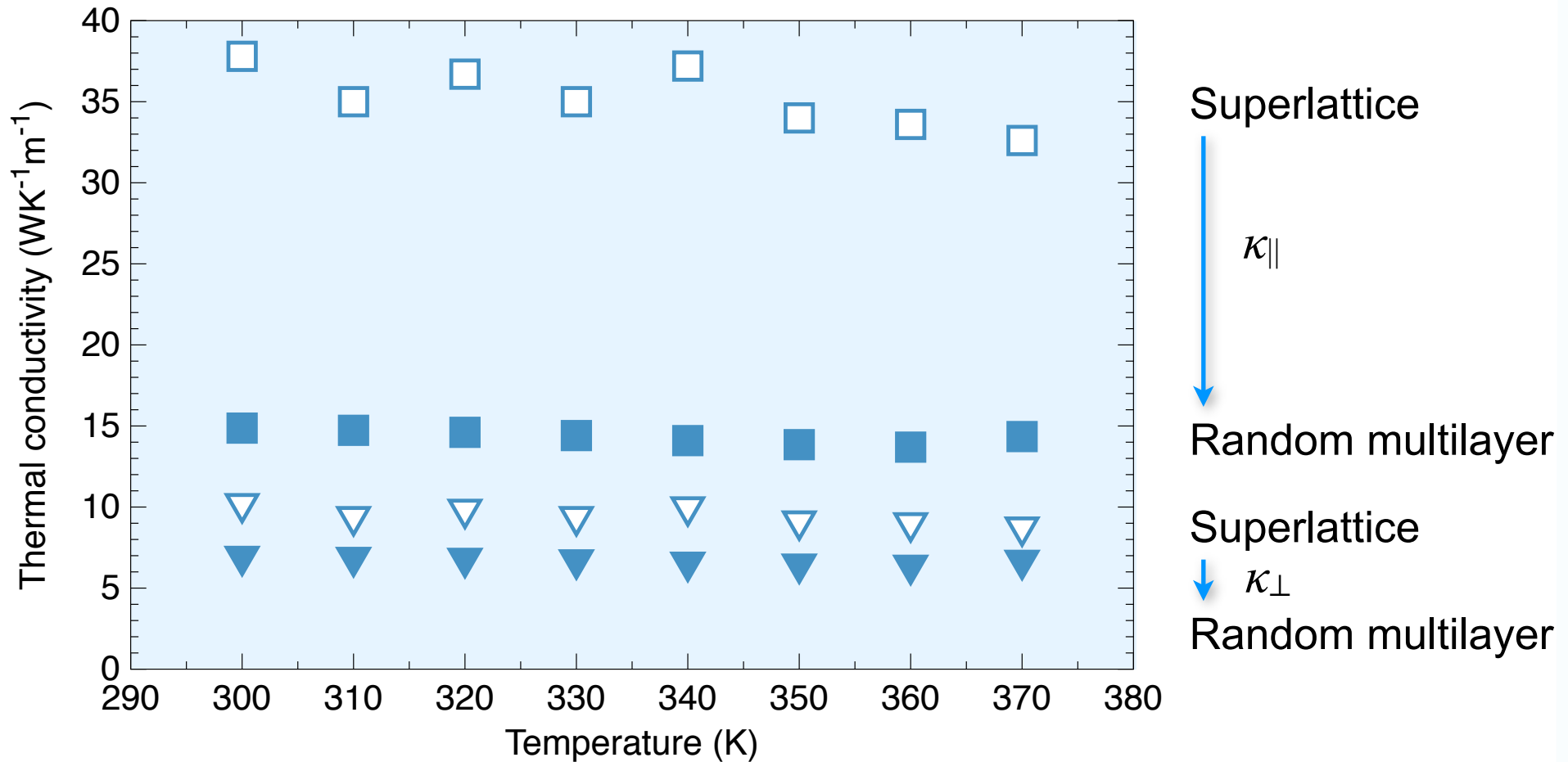
34x,  $\approx$  940 nm

Average Ge content

2.9 %

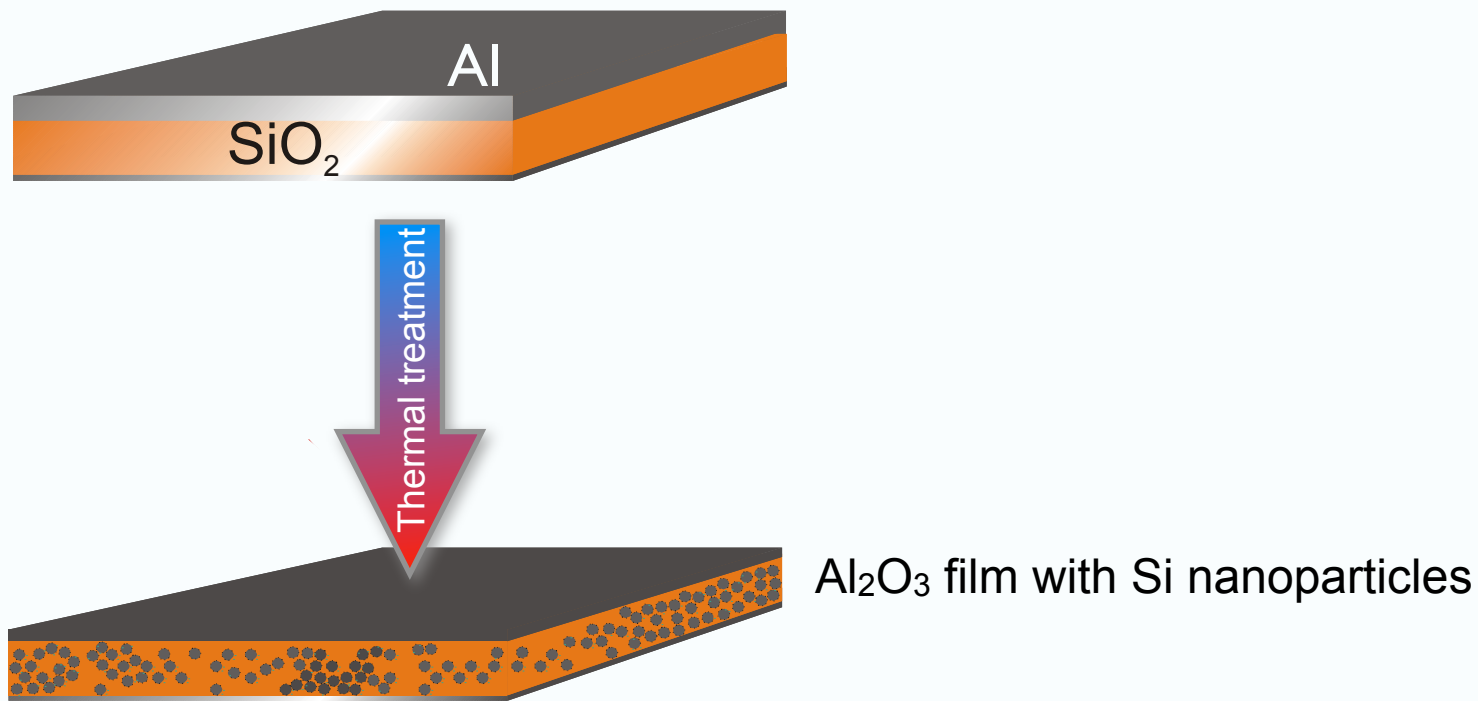
3.3 %

# 3 $\omega$ results of random multilayers



Thermal conductivities in a random multilayer (2.9 % Ge)  
in comparison to a superlattice (3.5 % Ge)

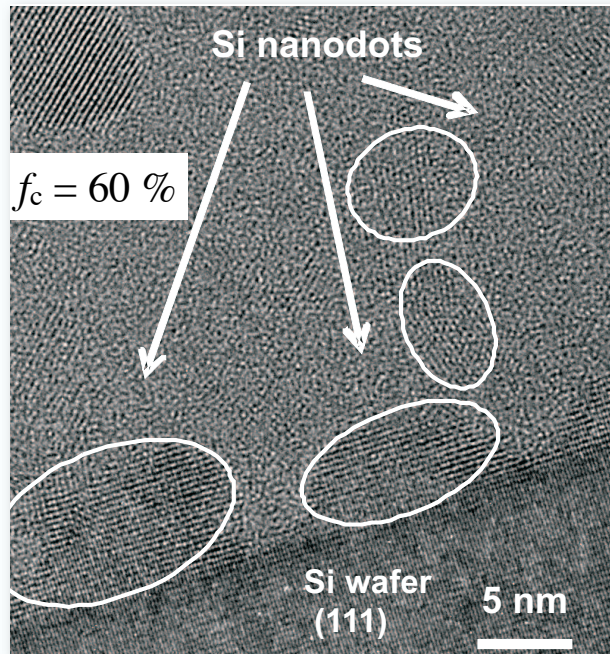
# Nanoparticles in thin-film oxide



## Fabrication of thin film 0–3 composites

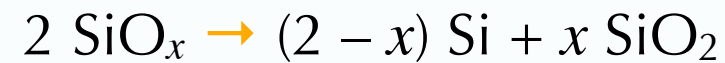
- ✦ Solid-state reaction  $3 \text{SiO}_2 + 4 \text{Al} \rightarrow 3 \text{Si} + 2 \text{Al}_2\text{O}_3$
- ✦ PECVD deposition of  $\text{SiO}_x$  and subsequent crystallization to form Si nanodots at the percolation limit;  $2 \text{SiO}_x \rightarrow (2 - x) \text{Si} + x \text{SiO}_2$

# Oxide-embedded Si nanodots



The degree of crystallization  $f_c$  depends on the oxygen content  $x$  in the SiO <sub>$x$</sub>  film.

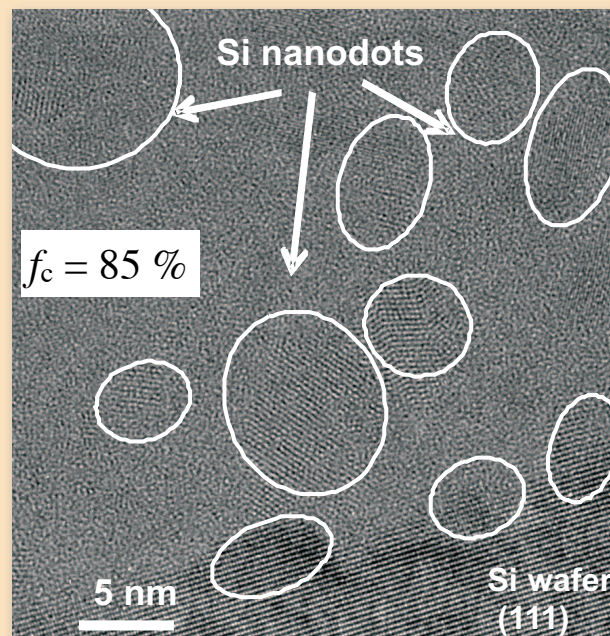
[Roczen *et al* / J Non-Cryst Sol 2011]



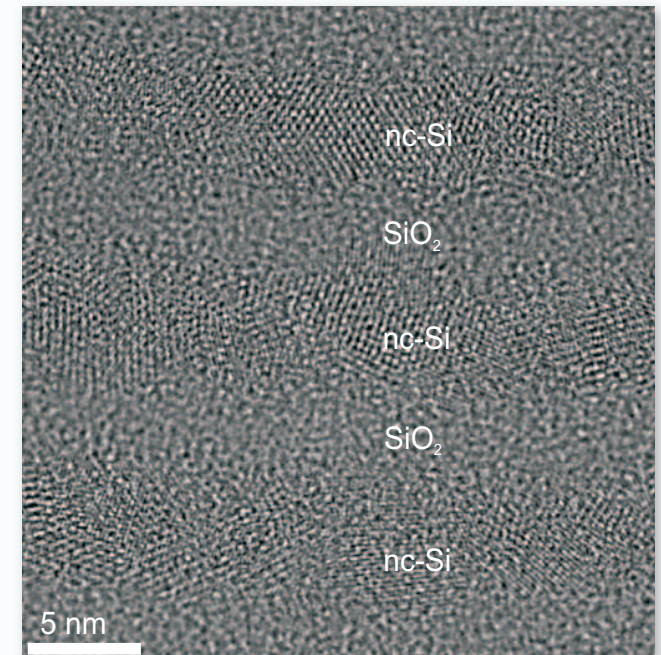
SiO<sub>1.3</sub>

Layer structure of nc-Si in SiO<sub>2</sub>

Percolation limit



SiO<sub>0.1</sub>

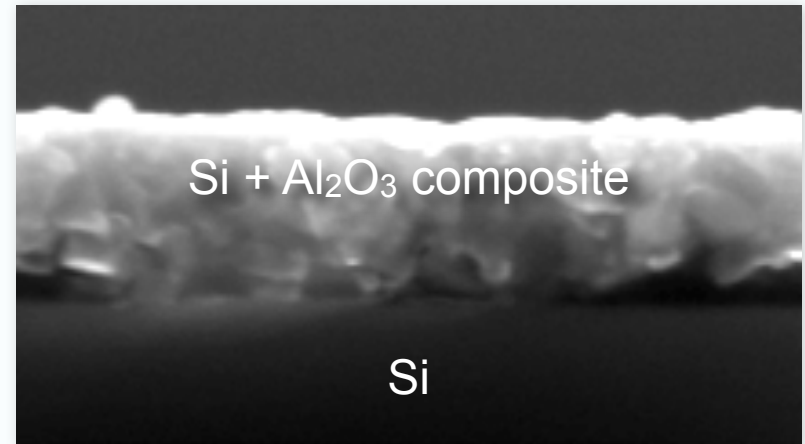
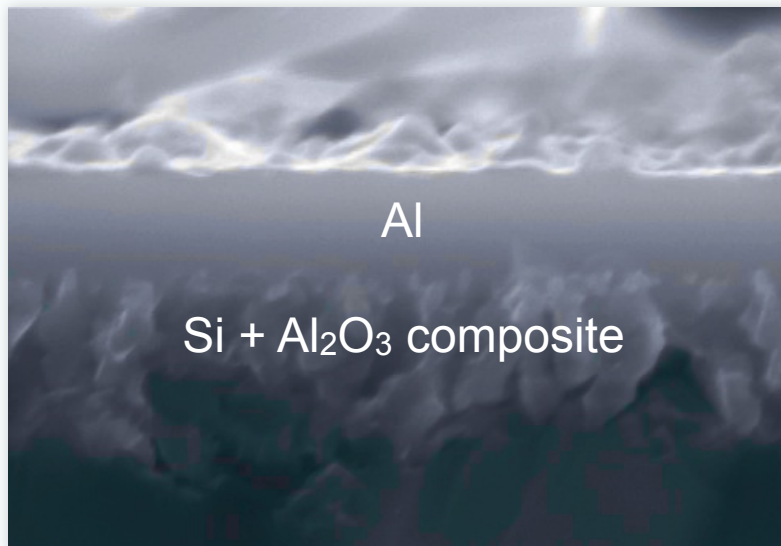
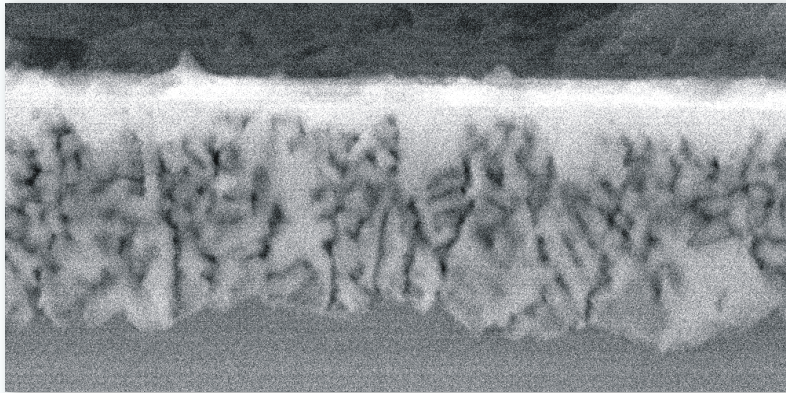




# Synthesis of Si particles in $\text{Al}_2\text{O}_3$

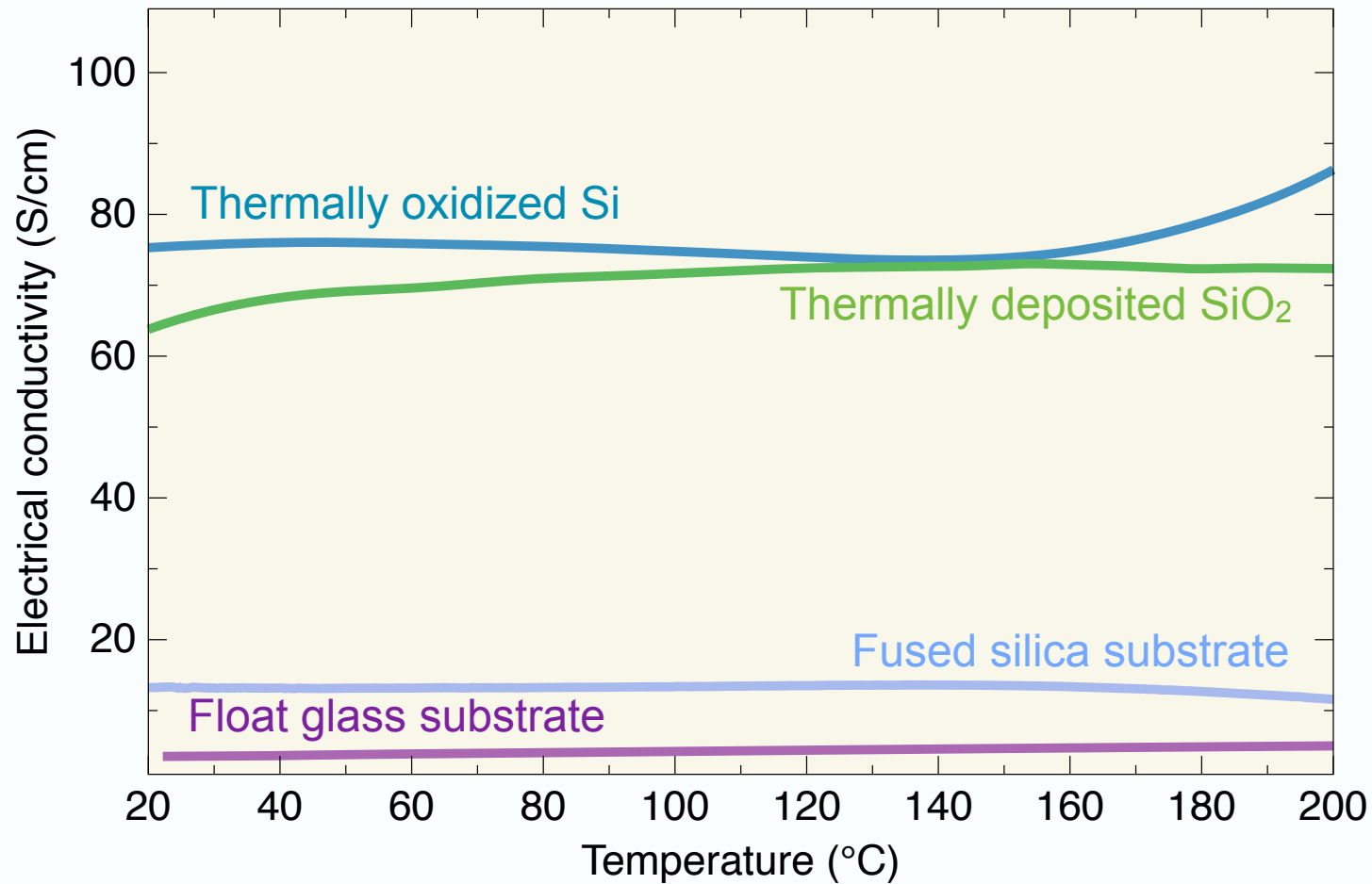
## Process parameters

- ✦ Initial thicknesses  $d_{\text{Al}}$ ,  $d_{\text{SiO}_2}$ , temperature (500...600 °C), annealing time (1...3 h)
- ✦ Reaction rate  $\approx 3$  nm/min at 550 °C
- ✦ Different substrates



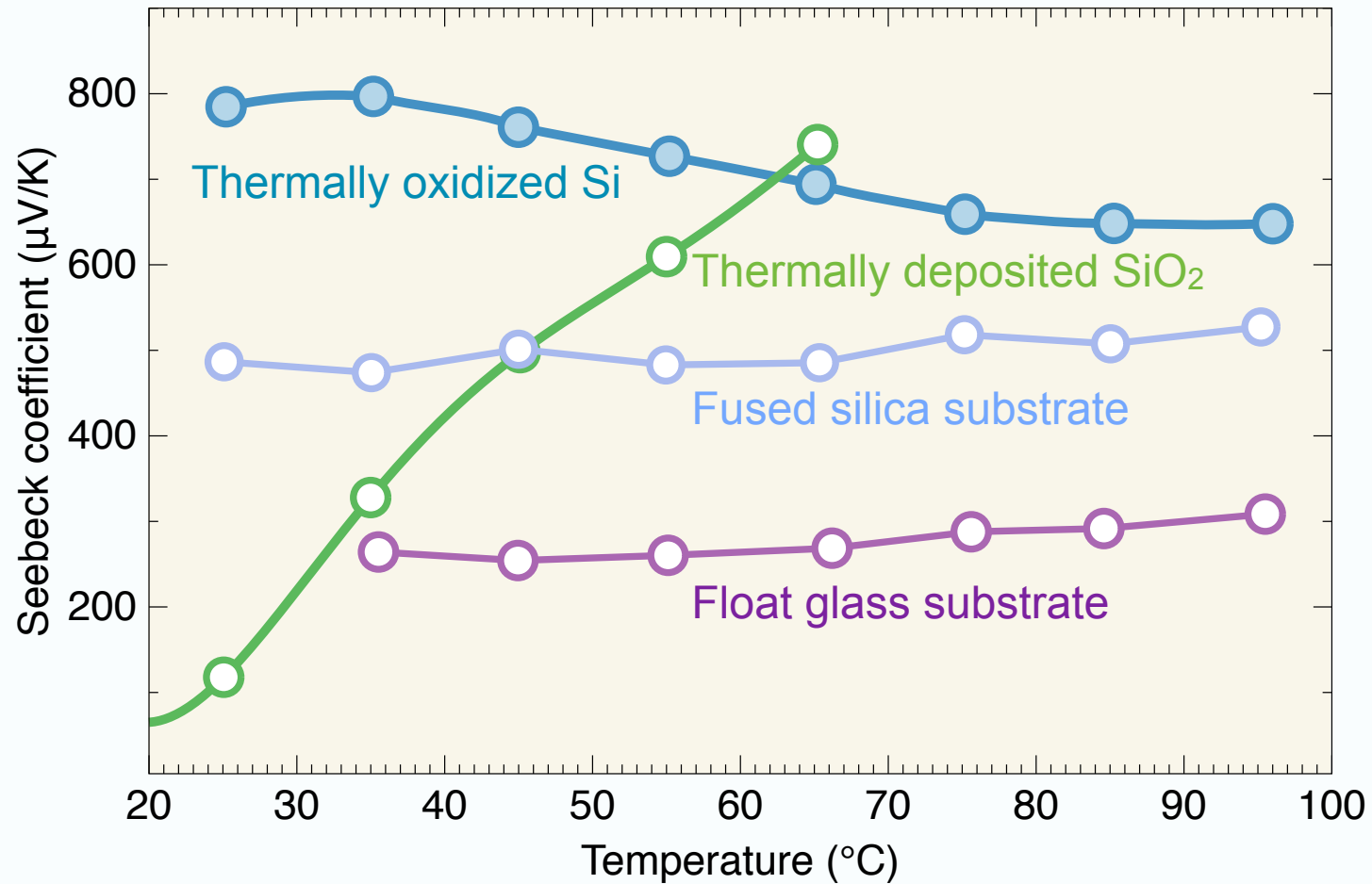
500 nm

# Electrical conductivity of Si–Al<sub>2</sub>O<sub>3</sub> films



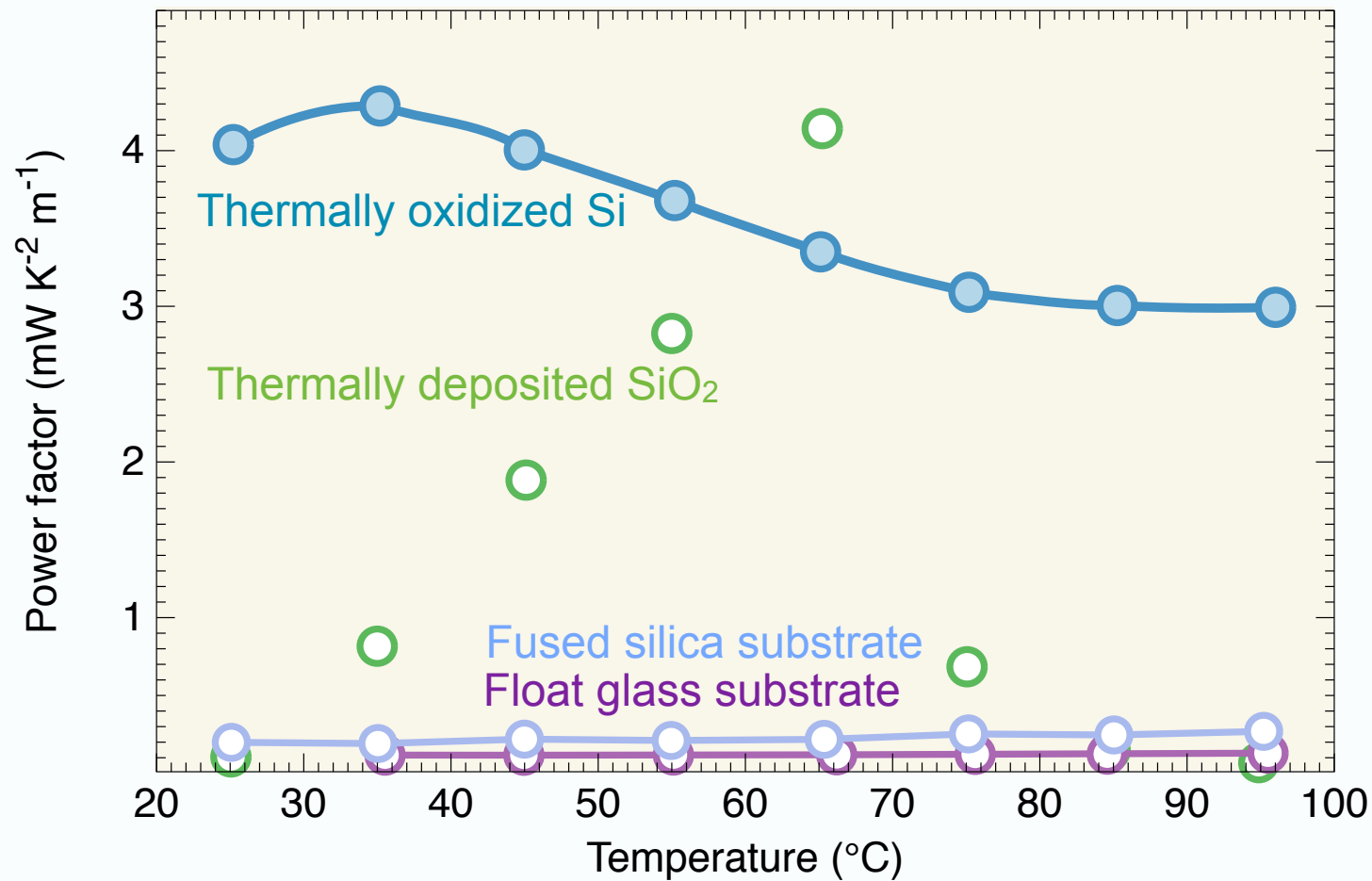
Electrical conductivity  $\sigma$  of the composite film for different substrates used

# Seebeck measurements of Si-Al<sub>2</sub>O<sub>3</sub> films



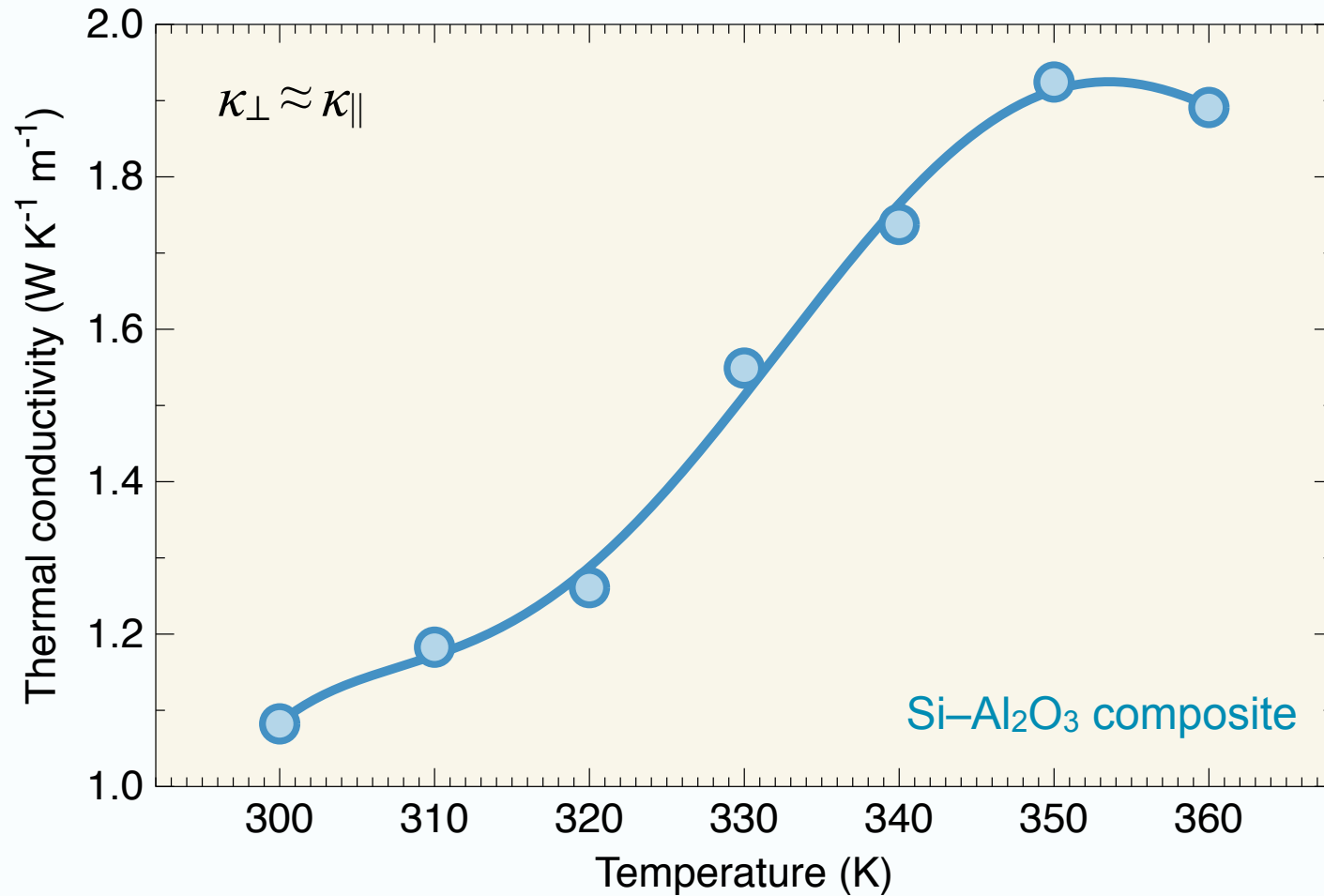
Seebeck coefficient  $S$  of the composite film for different substrates used

# Power factor of Si–Al<sub>2</sub>O<sub>3</sub> films



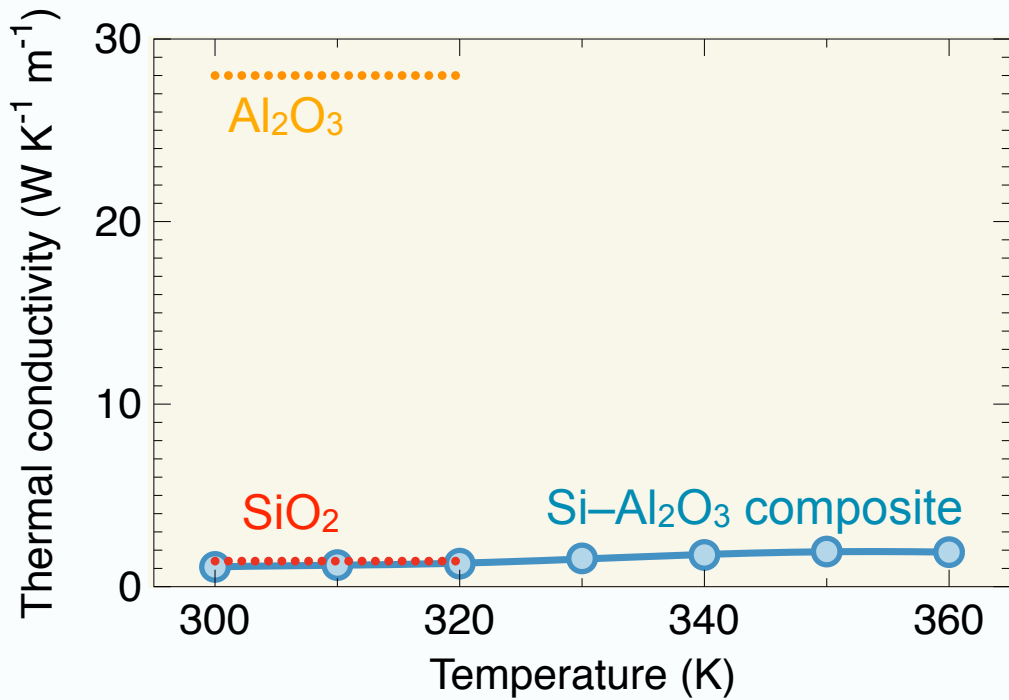
Power factor  $S^2\sigma$  of the composite films

# Comparison of thermal conductivities



Thermal conductivity  $\kappa$  of the composite film formed in thermally oxidized silicon

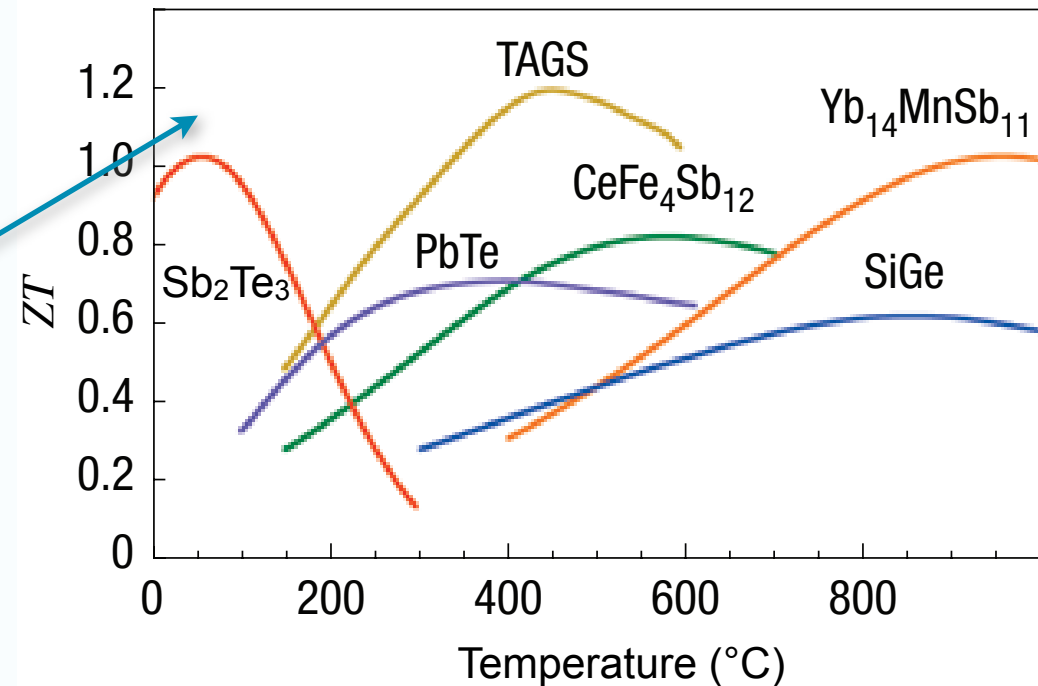
# Comparison of Si-Al<sub>2</sub>O<sub>3</sub> films



$ZT = 1.1$  @ 300 K for  
Si-Al<sub>2</sub>O<sub>3</sub> composites  
in thermally oxidized Si

Figure of merit for different materials

[Snyder 2008]



# Summary

- ◆ **Control of the phonon propagation**

Periodic → Aperiodic Si–SiGe multilayers

- ◆ **Realization of the electron crystal–phonon glass concept**

Thermoelectric transport in oxide-embedded nanoparticles

- ◆ **Thermoelectric properties:**

- $\sigma \approx 150 \text{ S/cm}$ ,  $S \approx 500 \text{ } \mu\text{V/K}$ ,  $\kappa_{\perp} < 5 \text{ W/(K}\cdot\text{m)}$

for highly doped Si–Si<sub>1-x</sub>Ge<sub>x</sub> aperiodic multilayers

- $\sigma \approx 100 \text{ S/cm}$ ,  $S > 600 \text{ } \mu\text{V/K}$ ,  $\kappa \approx 1 \text{ W/(K}\cdot\text{m)}$

for Si-based 0–3 composites

- ◆ **Figure of merit**

$ZT > 1$  at 300 K for optimized Si-based thin films

# Acknowledgments

- ◆ Martin Schade, Andreas Kipke, Frank Syrowatka, Frank Heyroth, Georg Schmidt (CMAT Halle)
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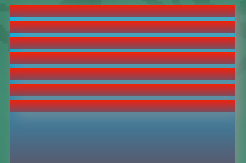


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# References

- ◆ LD Hicks, MS Dresselhaus: Phys Rev B **47** (1993) 12727.
- ◆ GJ Snyder, ES Toberer: Nature Mater **7** (2008) 105.
- ◆ M Roczen *et al* J Non-Cryst Sol (2011) [10.1016/j.jnoncrysol.2011.11.024](https://doi.org/10.1016/j.jnoncrysol.2011.11.024)